



Material Content Data Sheet



Sales Product Name	IFX8117ME V33			Issued		29. August 2013		
MA#	MA000832208							
Package	PG-SOT223-4-18			Weight*		112.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.302	1.16	1.16	11558	11558
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		90	
	non noble metal	titanium	7440-32-6	0.051	0.05		452	
	non noble metal	chromium	7440-47-3	0.153	0.14		1356	
	non noble metal	copper	7440-50-8	50.679	45.01	45.21	450023	451921
wire	noble metal	gold	7440-57-5	0.321	0.28	0.28	2846	2846
encapsulation	organic material	carbon black	1333-86-4	0.460	0.41		4081	
	plastics	brominated resin	-	0.575	0.51		5102	
	inorganic material	antimonytrioxide	1309-64-4	1.149	1.02		10203	
	plastics	epoxy resin	-	10.456	9.28		92850	
	inorganic material	silicondioxide	60676-86-0	44.812	39.79	51.01	397929	510165
leadfinish	non noble metal	tin	7440-31-5	1.464	1.30	1.30	13000	13000
plating	noble metal	silver	7440-22-4	0.768	0.68	0.68	6817	6817
glue	plastics	epoxy resin	-	0.073	0.06		646	
	noble metal	silver	7440-22-4	0.343	0.30	0.36	3047	3693
*deviation	< 10%				Sum in total:		100,00	1000000

Important Remarks:

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